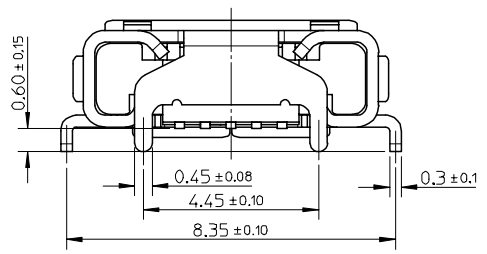
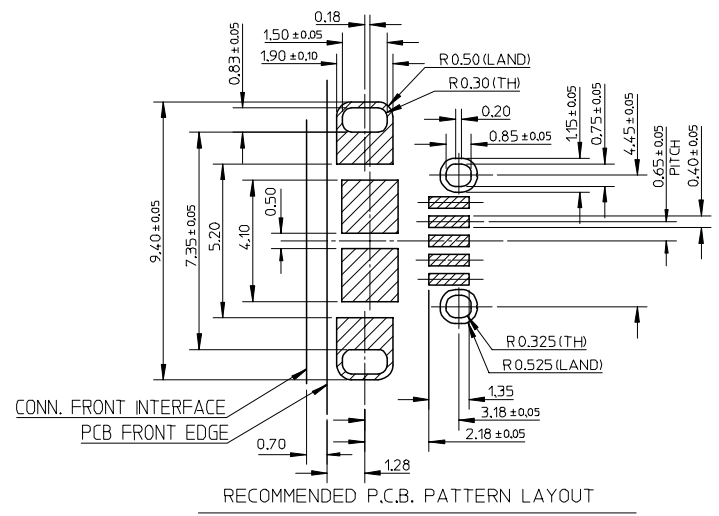


NOTE :

- MATERIAL :
HOUSING : LCP, BLACK, UL94V-0
TERMINAL : COPPER ALLOY THICKNESS = 0.15 MM
SHIELD CASE : STAINLESS STEEL THICKNESS = 0.30 MM
- PLATING :
TERMINAL: CONTACT AREA : GOLD FLASH (0.11 MICRON MIN.) OVER MINIMUM 0.75 MICRON Pd/Ni.
SOLDER TAIL AREA : GOLD FLASH (0.05 MICRON MIN.).
UNDER PLATING : NICKEL 2.0 MICROMN MINIMUM.
SHIELD : MATTE TIN 1.27 MICRON MINIMUM.
UNDER PLATING : NICKEL 1.27 MICRON MINIMUM.
- TAIL COPLANARITY 0.08 MM MAXIMUM.
- COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV DIRECTIVE 2000/53/EC.



NEW RELEASE EC NO: SH2008-0069 DRWN: XJSONG CHKD: JTIAN APPR: HWANG	QUALITY SYMBOLS ▽=0 △=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
						DRAWN BY XJSONG	DATE 2007/03/06	TITLE MICRO USB AB REC. BOTTOM MOUNT ASS'Y		
						CHECKED BY JTIAN	DATE 2007/03/06			
						APPROVED BY JNCHEN		DATE 2007/03/06	MOLEX INCORPORATED	
A	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. 47589-0001		DOCUMENT NO. SD-47589-001		SHEET NO. 1 OF 1		